



**PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No: 10/621,987                      Docket No: 2011118  
Filing Date: 07/16/2003                  Applicant: Jackson Hsieh  
Examiner: SOWARD, IDA M                  Art Unit: 2822  
Title: SUBSTRATE STRUCTURE FOR AN INTEGRATED CIRCUIT PACKAGE  
AND METHOD FOR MANUFACTURING THE SAME

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO OFFICE ACTION**

Dear Sir:

In response to the Office Action dated 03/12/2004, Applicant submits the following.

**ELECTION**

1. Applicant elects to restrict this application to the species designated by the Examiner as Species I, relating to Figs. 1-5, and directed to claims 1-3 and 5-6.

Respectfully submitted,

Date: April 13, 2004

  
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Keith Kline  
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**CERTIFICATE OF MAILING (37 CFR 1.8a):** I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: April 13, 2004

  
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Keith Kline